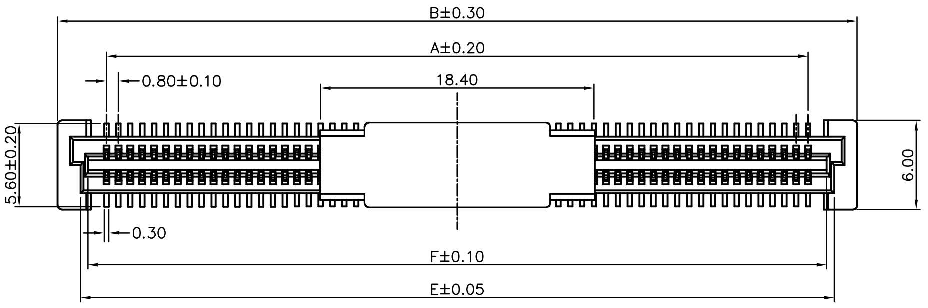
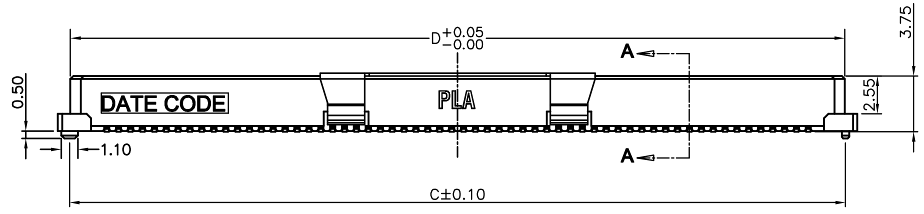
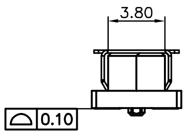
REV	ECN. NO.	DESC.	APPD.
A	WE210842	新版发行	LWW 210820



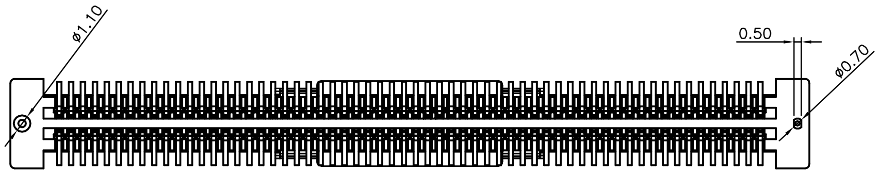


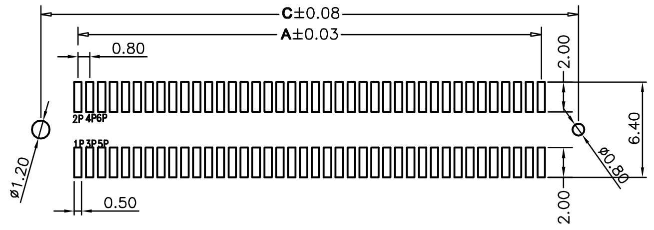


NOTES: (UNLESS OTHERWISE SPECIFIED)

1. DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M−1994
2. INSERTION FORCE: 150g MAX. PER CONTACT.
3. WITHDRAW FORCE: 25g MIN. PER CONTACT.
4. DURABILITY: 30 CYCLES .
5. VOLTAGE RATING:50V AC
6. CURRENT RATING:0.5 AMPERE.
7. CONTACT RESISTANCE:50 m ohms MAX. FOR INITIAL.
8. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms./MINUTE.
9. INSULATION RESISTANCE: 100 Megohms MIN..
10. HARMFUL MATERIAL SHOULD BE COMPLIANT TO STANDARDS.
11. PRODUCT NUMBER MATRIX:5001−BAP 0837−** F R-00-B

Standby
PACKING:R:REEL
FEMALE
PIN
MATINGHEIGHT: 37-3.7H
0.8BTB
JM CONN BTB CONNECTOR SERIES





RECOMMEND PCB LYOUT TOLERANCE ±0.05

CIRCUITS	DIM.A	DIM.B	DIM.C	DIM.D	DIM.E	DIM.F
40	15.20	21.80	20.20	20.10	18.70	17.70
60	23.20	29.80	28.20	28.10	26.70	25.70
80	31.20	37.80	36.20	36.10	34.70	33.70
100	39.20	45.80	44.20	44.10	42.70	41.70
120	47.20	53.80	52.20	52.10	50.70	49.70
140	55.20	61.80	60.20	60.10	58.70	57.70
160	63.20	69.80	68.20	68.10	66.70	65.70
180	71.20	77.80	76.20	76.10	74.70	73.70
200	79.20	85.80	84.20	84.10	82.70	81.70

X.±0.30	.X± 0.25	.XX± 0.20
X.°± 3°	.X°± 2°	.XX°±
UNITS: mm	DATE: 2021-08-20	
MAT'L		

NAME<INTENDED USE>: 0.8MM BTB RECEP.

东莞市文章济美电子有限公司

PART NO.<INTENDED USE>: 5001-BAP0837-**FR-00-B

TITLE: CUSTOMER DRAWING

APPD:

CHKD:

DR:

DWG NO.: 600-0000-0528

SCALE	SHEET	REV
N/A	1/4	A

1. SCOPE

This product specification contains the test method, the general performance and property for 0.8 Pitch Board To Board connector

2. General items:

2.1 Application

This specification applies to the0.8 Pitch Board To Board connector

2.2 Operating Temperature Range: -40~105 ºC

2.3 Storage Temperature Range: -40~85 ºC

3. PROPERTY

3.1 MATERIALS

Item	**Standard**
Housing	**High Temperature Thermoplastic , UL 94V-0**
Contact	**Copper Alloy, Gold plating**

3.2 RATINGS

Item	**Standard**
Current Rating	**0.5 A AC/DC Max.**
Voltage Rating	**50V AC/DC**
Ambient Temperature Range	**-40℃ ~ +105℃**
Storage Temperature Range	**-40℃ ~ +85℃**
Ambient ` Range	**95％ R.H. Max.**

4. Test Methods and Requirements:

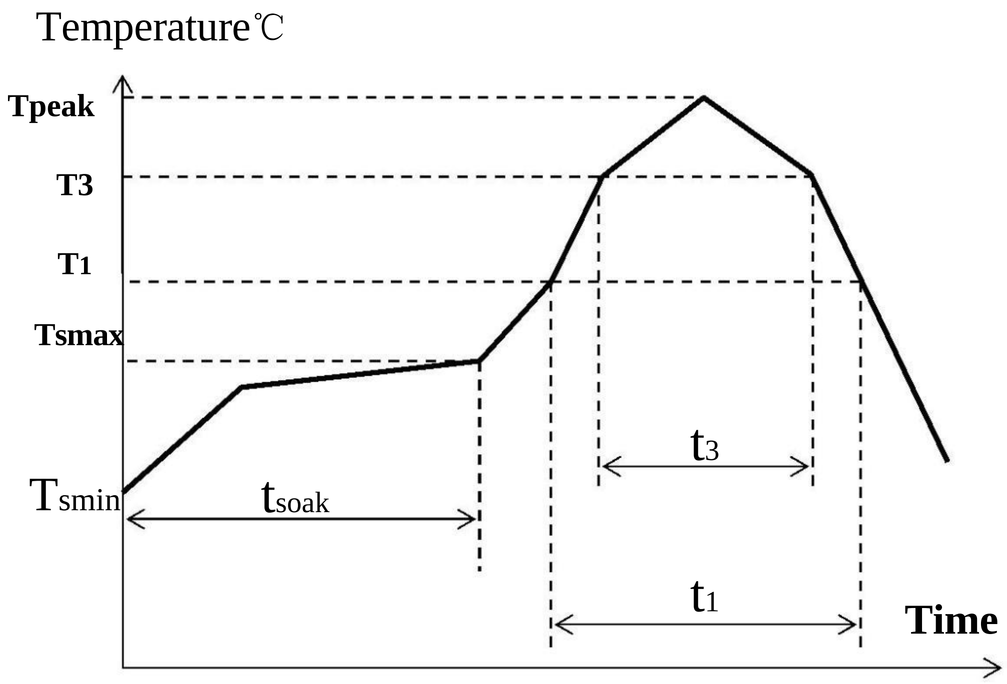
4.1 Electrical Performance

Item	Test Item	Standard	Test Condition
4.1.1	Contact Resistance	It should be tested in accordance. (EIA-364-23)	50 mΩ max. Initial
4.1.2	Insulation Resistance	Apply a voltage of AC 500V for 2 minutes between adjacent terminals and measure. (EIA-364-21C)	100 MΩ min. Initial 50 MΩ min. Final
4.1.3	Dielectric Withstanding Voltage	Apply a voltage of AC 500V for 60±5s to between adjacent terminals.	There must be no breakdown.
4.2 Mechanical Performance:			
4.2.1	Contact Retention force	Pull connectors at maximum rate of 25mm/minute.	200 grams min./per contact
4.2.2	Insertion force	Plug insert into socket shell be an alignment at a constant speed of 25mm/minute.	150gf Max per contact
4.2.3	Withdrawal force	Plug pull out socket shell be an alignment at a constant speed of 25mm/minute	25gf Min per contact
4.2.4	Durability	EIA-364-09C Connector shall be subjected to 30cycles of Insertion and withdrawal	50mΩ max. initial 70 mΩ max. Final

4.2.5	Vibration	10-55-10 Hz/min. Amplitude：1.52mm Period：2 hours for each direction X,Y,Z axis. (EIA-364-28E)	No electrical discontinuity greater than 1 microseconds shall occur.
4.2.6	Drop	76cm Height one carton 6-sydes random dropping.	[Appearance] No abnormality [Function] OK
4.3 Environmental Performance:			
4.3.1	Thermal shock	EIA-364-32C, Condition I. One cycle consists of： -55℃ for 30 minutes/+85℃ for 30 minutes. Times of cycle：5 cycles.	See Note 50mΩ max. initial 70 mΩ max Final
4.3.2	Humidity	EIA-364-31B, Method II, Condition A Temperature：40 ±2℃ Humidity：90 ~ 95 % (RH) Period：96 hours	See Note 50mΩ max. Initial 70 mΩ max Final
4.3.3	Salt Spray	EIA-364-26B, Condition A. Temperature：35±2℃ , Density 5% in weight. Period24 hours	50mΩ max. initial 70 mΩ max Final
4.4 Others			
4.4.1	Solder ability	EIA-364-52 Temperature：245+/-5℃,3~5sec	See Note 95%min
4.4.2	Temperature Life	EIA-364-17A, method A Condition 4. Temperature： 105 ± 2 ℃ Period250 hours	See Note 70 mΩ max Final
NOTE：Shall meet visual requirements , show no physical damages.			

5. Reflow Profile for soldering heat resistance testing

Reflow Profile for soldering heat resistance testing		
Parameter	Mark	Major parts
Speed of temperature-raising		Not raise over 3℃ for each second
Temperature Min (Ts min)	Ts min	150℃
Temperature Max (Ts max)	Ts max	200℃
Time (ts min to ts max)	Ts	2~3minutes
Time of temperature over 217℃	t 1	60~150seconds
At the reflow area	t 3	20~40 seconds (t 3)
	T3	(T3)
At the highest temperature	T peak	260(+0/-5℃)
Speed of temperature-decreasing		Not decrease over 6℃ for each second
Time from 25℃ to highest temperature		Not over 8 minutes



SMT TYPE Re-flow profile for soldering heat(Lead free)

6. PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUEN

Test Item	Test Group								
	A	B	C	D	E	F	G	H	I
Appearance	1	1	1,5	1	1,5	1,7	1,5	1,5	1.5
Contact Resistance			2.4		2.4		2.4	2.4	2.4
Insulation Resistance						2,6			
Dielectric Withstanding Voltage						3,5			
Contact retention force		2							
Insertion force	2								
Retention Force	3								
Durability			3						
Vibration									3
Thermal Shock						4			
Humidity					3				
Salt Spray							3		
Temperature Life								3	
Solder ability				2					
Sample QTY	5	5	5	5	5	5	5	5	5